

CLAIM AMENDMENTS

1-15. (Canceled)

16. (Currently amended) A pressure sensor according to Claim ~~[[15]]~~ 17, wherein said anaerobic adhesive is a polymethacrylic adhesive.

17. (Currently amended) A pressure sensor ~~according to Claim 15,~~
comprising metallic terminals, a resin material molded integrally with said
metallic terminals, and a semiconductor sensor and therefor a signal processing
circuit placed in said resin material,

wherein an anaerobic adhesive is filled in gaps between said metallic
terminals and said resin material after integrally molding said resin material
with said metallic terminals, and

wherein said semiconductor sensor and therefor said signal processing circuit are placed in an outer resin case, said outer resin case being molded integrally with metallic lead members for outputting a processed signal of said signal processing circuit, and the anaerobic adhesive is filled in gaps between said metallic lead members and said resin material after integrally molding said outer resin case with said metallic lead members.

18. (Canceled)

19. (Currently amended) A pressure sensor according to Claim ~~[[18]]~~ 20, wherein said high-permeability adhesive is an acrylic adhesive.

20. (Currently amended) A pressure sensor ~~according to claim 18,~~
comprising metallic terminals, a resin material molded integrally with said
metallic terminals, and a semiconductor sensor and therefor a signal processing
circuit placed in said resin material,

wherein a high-permeability adhesive is filled in gaps between said
metallic terminals and said resin material after integrally molding said resin
material with said metallic terminals, and

wherein said semiconductor sensor and therefor said signal processing circuit are placed in an outer resin case, said outer resin case being molded integrally with metallic lead members for outputting a processed signal of said signal processing circuit, and the high-permeability adhesive is filled in gaps between said metallic lead members and said resin material after integrally molding said outer resin case with said metallic end members.

21-30. (Canceled)